

EVG and Dymek form joint venture in Malaysia – June 1, 2023

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EVG and Dymek form joint venture in Malaysia EV Group Malaysia Dymek to provide customer support in SE Asia

EV Group of St Florian, Austria — a supplier of wafer bonding and lithography equipment for semiconductor, micro-electro-mechanical systems (MEMS) and nanotechnology applications — and Dymek Co Ltd of Hong Kong, an equipment distributor for the semiconductor, biomedical, data storage, photovoltaic and aerospace industries, have established a new joint venture company in Penang, Malaysia.

EV Group Malaysia Dymek Sdn Bhd will be charged with managing EVG's customer support operations in Malaysia. Hermann Waltl, executive sales & customer support director and member of the executive board at EVG, will serve as director of the new joint venture, and Sean Lim from Dymek will serve as managing director.

Working closely with EVG's headquarters, EV Group Malaysia Dymek will be responsible for numerous key regional customer support activities, including equipment installation, technical service and

support, spare-parts management and supply, and process development support. The company will be fully operational in July.

"Malaysia has been an important center for semiconductor and microelectronics packaging, test and assembly for several decades. As global investments from leading chip manufacturers and outsourced semiconductor assembly & test companies in the region continue to ramp up, it is vital that EVG strengthen its customer support infrastructure here as well," says Waltl. "Dymek has been a key strategic partner for EVG in several countries in Asia already for many years, and we look forward to partnering with them to enhance our customer support in Malaysia as well," he adds.

"This strategic move by EV Group to establish a more direct presence in Malaysia will be well received by the semiconductor and microelectronics industries of Southeast Asia," Stanley Lam, managing director Asia Pacific at Dymek Company.

"Companies here already recognize EVG as a market and technology leader in semiconductor process equipment, and now knowing they can receive local support from local engineers will only further increase their confidence and trust in EVG," he adds. "We are pleased to be working closely with EVG to grow and enhance their customer support infrastructure in Malaysia and across Southeast Asia."

EVG at SEMICON Southeast Asia

EVG was a sponsor and program speaker at SEMICON Southeast Asia at the Setia SPICE Convention Centre in Penang (23–25 May). Attendees heard about EVG's latest developments in heterogeneous integration at the Advanced Packaging Forum, where Dr Thorsten Matthias, regional sales director Asia-Pacific for EVG, presented on state-of-the-art and upcoming requirements in wafer-to-wafer and die-to-wafer hybrid bonding.

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